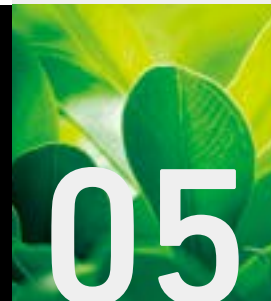


高屈曲でありながら高解像度 / 従来より簡便な工程でより薄いFPCを実現

High resolution with excellent flexibility /
Thinner FPC with simpler process



05

感光性カバーレイ FLEXFINER Series

Photo Imageable Coverlay FLEXFINER Series

特長 Features

- **高解像性と高屈曲性の両立を実現した感光性ポリイミドフィルム**
Photo imageable polyimide film with high resolution and high bendability
- **現行のプリント配線板製造ラインへの適用を実現**
Applicable to current PWB photolithography process
- **優れた耐熱性と絶縁信頼性と難燃性 (VTM-0)**
Excellent heat resistance, insulation reliability and flame resistance (VTM-0)
- **各種電磁波シールドに対する優れた層間絶縁信頼性**
Excellent interlayer insulation with various type of EMI shield

特性 Properties

はんだ耐熱性 Solderability

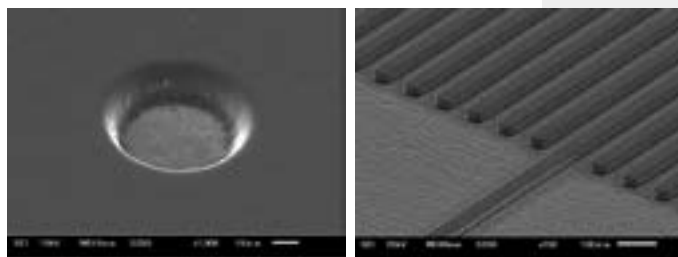
288°C x 10s x 3times No delamination

屈曲性 Bendability

Folding: 20cycles (R=0mm)
MIT: 1000cycles (R=0.38mm)
IPC: 10,000,000cycles or more (R=5mm)

絶縁信頼性 Insulation Reliability

L/S=25/25 85°C 85% D.C. 100V / 96Hrs + D.C. 50V / 404Hrs Pass
L/S=12/13 120°C 85% D.C. 60V 200hrs Pass
L/S= 8/ 8 130°C 85% D.C. 5V 200hrs Pass



Item	Amber Type					Black Matte Type	
	15SA	20SA	25SA	30SA	40SA	30EM-L	40EM-L
Film Thickness	15μm	20μm	25μm	30μm	40μm	30μm	40μm
Shelf life	24 Months at -15°C						

用途 Application

- **モバイル・ウェアラブル Mobile・Wearable**
高密度FPC、FPCの薄膜化、
低スティフネスアプリケーション
High Density FPC, Thinner FPC, Applications requiring low stiffness

- **ロボティクス Robotics**
優れた摺動屈曲性を生かした
ダイナミックアプリケーション
Dynamic applications with excellent bending property